

FIG. 1

HOLOGRAM-MAGNETIC RECORDING LAYER : 2

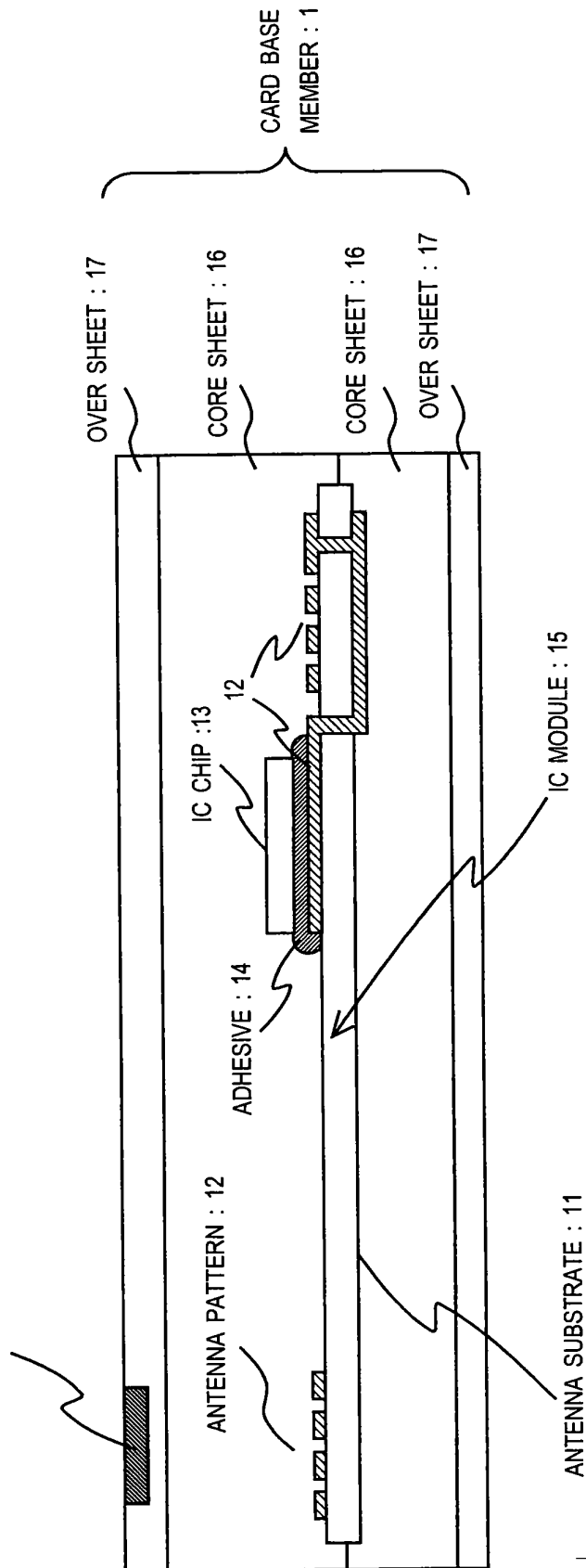


FIG. 2

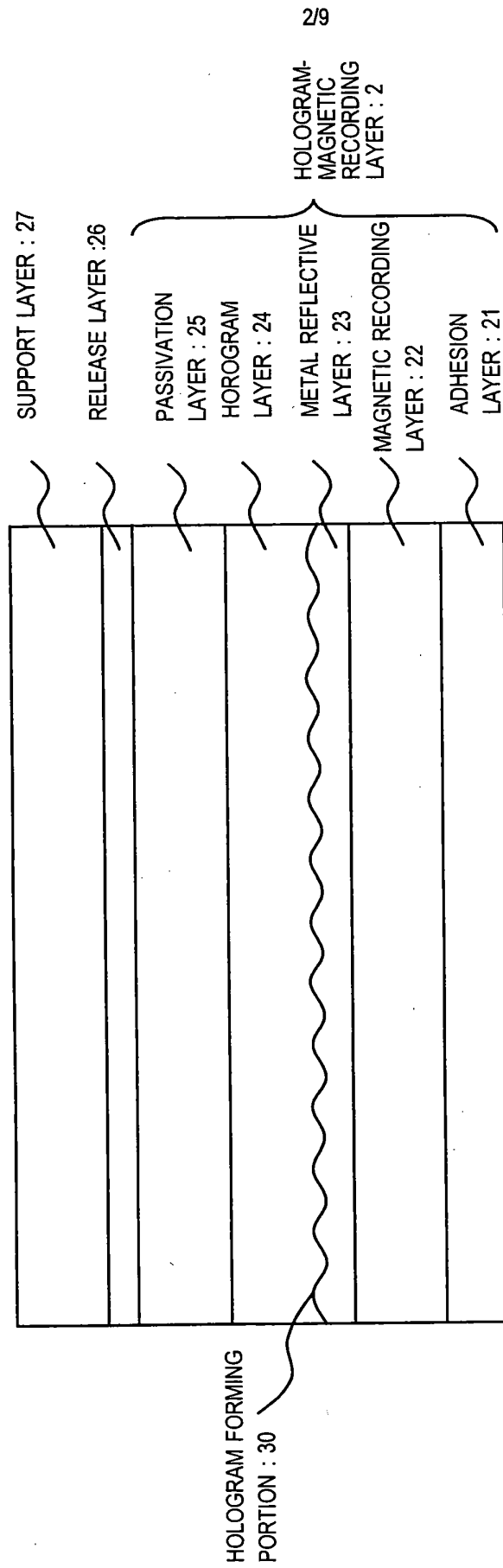


FIG. 3

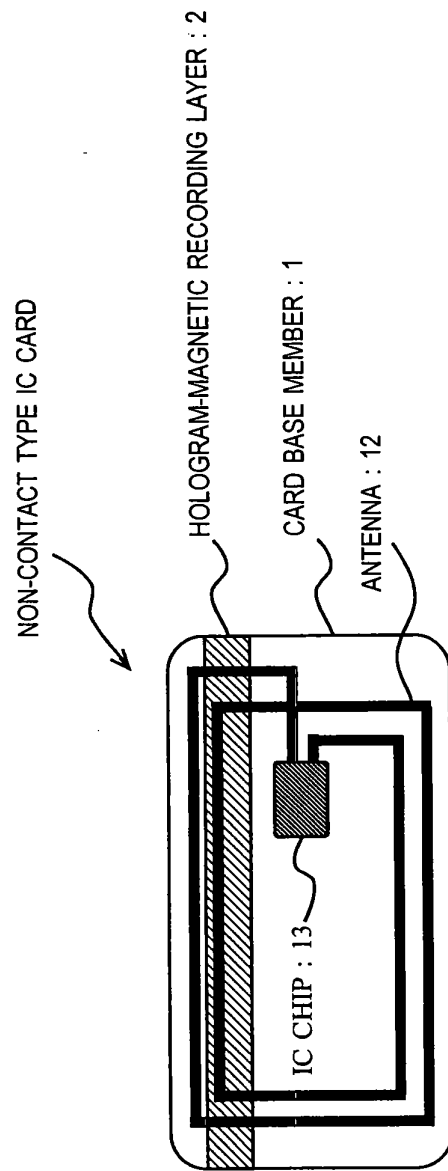


FIG. 4

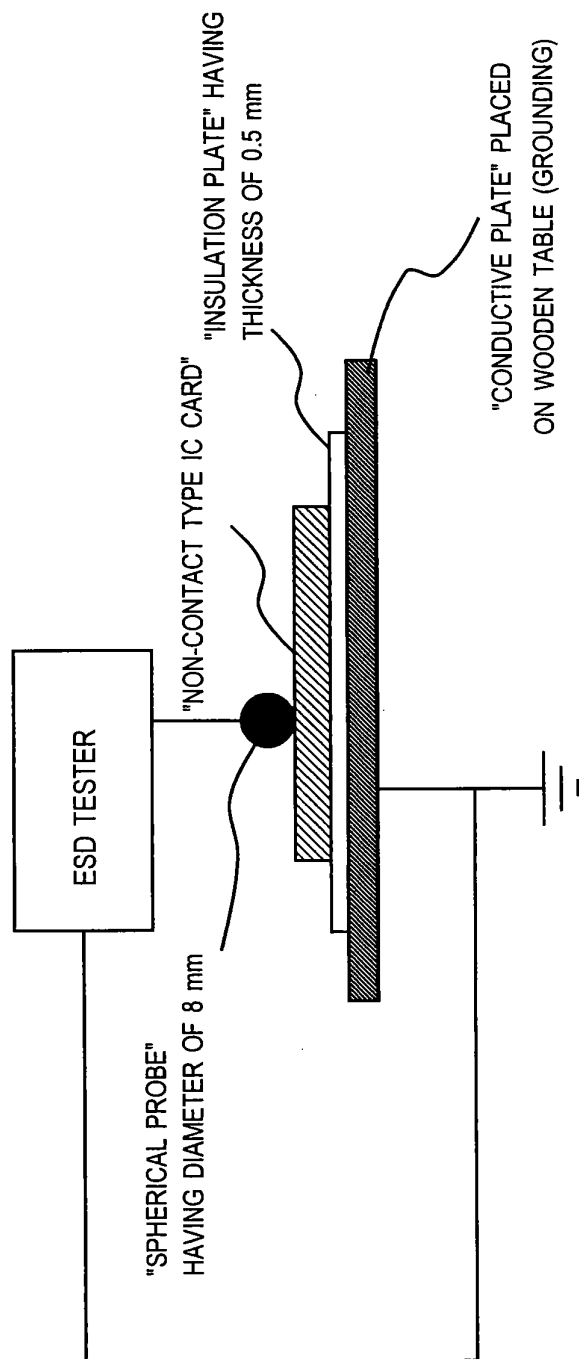


FIG. 5

NON-CONTACT TYPE IC CARD



1	2	3	4	5
6	7	8	9	10
11	12	13	14	15
16	17	18	19	20

FIG. 6

MATERIAL OF METAL REFLECTIVE LAYER	ELECTRIC CONDUCTIVITY $\sigma \times 10^6$ [Ωm] TEMPERATURE CONDITION OF 20°C	PRESENCE OR ABSENCE OF ELECTROSTATIC DISCHARGE FAILURE OF IC CHIP
Ag	62.9	PRESENCE
Cu	59.3	PRESENCE
Al	36.9	PRESENCE
Au	28.9	PRESENCE
Zn	16.8	ABSENCE
Co	15.7	ABSENCE
Ni	14.2	ABSENCE
In	11.3	ABSENCE
Fe	9.9	ABSENCE
Cr	7.5	ABSENCE
Ti	1.8	ABSENCE
Sn	1.0	ABSENCE

FIG. 7

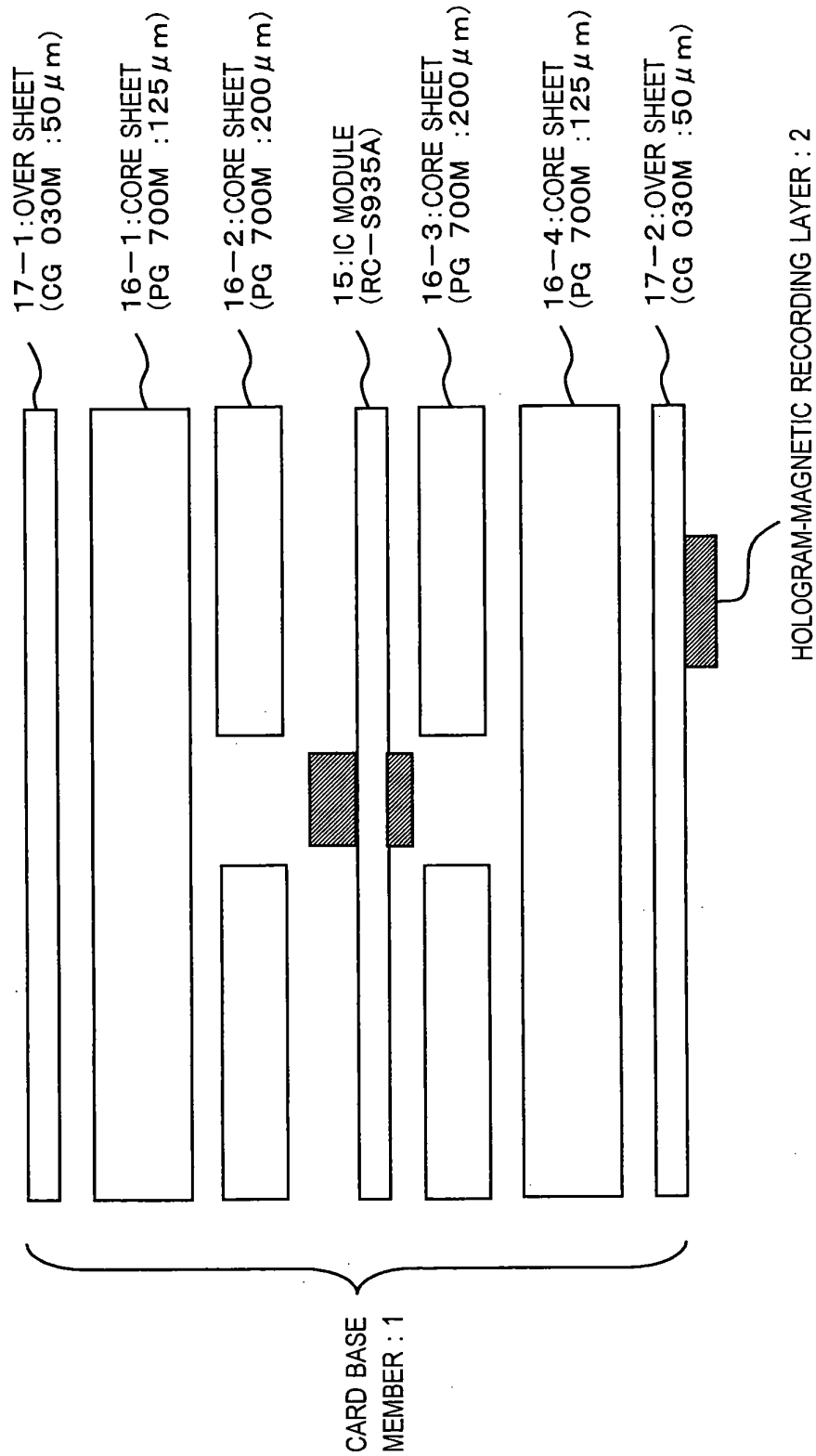


FIG. 8

SURFACE RESISTIVITY OF METAL REFLECTIVE LAYER ($\Omega/\square$)	PRESENCE OR ABSENCE OF ELECTROSTATIC DISCHARGE FAILURE OF IC CHIP
1.58	PRESENCE
1.78	PRESENCE
1.87	PRESENCE
2.33	PRESENCE
4.04	PRESENCE
7.02	ABSENCE
7.24	ABSENCE
7.50	ABSENCE
8.02	ABSENCE
16.20	ABSENCE

FIG. 9

